

L Number	Hits	Search Text	DB	Time stamp
1	1490	((substrate ((circuit wiring) near board)) with (trace pattern) with (layout (laid adj out)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/11 08:03
2	128	((substrate ((circuit wiring) near board)) with (trace pattern) with (layout (laid adj out))) with pad	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/11 07:49
3	73	((((substrate ((circuit wiring) near board)) with (trace pattern) with (layout (laid adj out))) with pad) and array	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/11 07:49
4	67	((((substrate ((circuit wiring) near board)) with (trace pattern) with (layout (laid adj out))) with pad) and array) and (semiconductor chip die)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/11 07:59
5	479	leadless near1 package	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/11 07:56
6	193	(leadless near1 package) and (pad land) and array	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/11 07:57
7	192	((leadless near1 package) and (pad land) and array) not (((substrate ((circuit wiring) near board)) with (trace pattern) with (layout (laid adj out))) with pad) and array)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/11 07:57
8	138	((leadless near1 package) and (pad land) and array) and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/11 07:58
9	130	((leadless near1 package) and (pad land) and array) and (bump ball) and (pattern trace wiring wire)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/11 07:59
10	115	((leadless near1 package) and (pad land) and array) and (bump ball) and (pattern trace wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/11 07:58
11	127	((leadless near1 package) and (pad land) and array) and (bump ball) and (pattern trace wiring wire) and (semiconductor chip die)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/11 07:59
12	336004	(substrate carrier ((circuit wiring) near board)) with (trace pattern wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/11 08:04
13	46520	(bond bonding conductive) adj (land pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/11 08:28
14	8635	((bond bonding conductive) adj (land pad)) with (shape shaped configuration structure)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/11 08:28
15	3085	((substrate carrier ((circuit wiring) near board)) with (trace pattern wiring)) and (((bond bonding conductive) adj (land pad)) with (shape shaped configuration structure))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/11 08:07
16	3579	((bond bonding conductive) adj (land pad)) near3 (shape shaped configuration structure)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/11 08:07
17	1307	((substrate carrier ((circuit wiring) near board)) with (trace pattern wiring)) and (((bond bonding conductive) adj (land pad)) near3 (shape shaped configuration structure))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/11 08:08

18	1669	((bond bonding conductive) adj (land pad)) near3 (shape shaped configuration)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/11 08:08
19	689	((substrate carrier ((circuit wiring) near board)) with (trace pattern wiring)) and (((bond bonding conductive) adj (land pad)) near3 (shape shaped configuration))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/11 08:08
22	181	(((substrate carrier ((circuit wiring) near board)) with (trace pattern wiring)) and (((bond bonding conductive) adj (land pad)) near3 (shape shaped configuration))) and (grid near array) not (((substrate ((circuit wiring) near board)) with (trace pattern) with (layout (laid adj out))) with pad) and array) not (((((leadless near1 package) and (pad land) and array) and (bump ball)) and (pattern trace wiring wire)) and (semiconductor chip die))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/11 08:10
21	189	((substrate carrier ((circuit wiring) near board)) with (trace pattern wiring)) and (((bond bonding conductive) adj (land pad)) near3 (shape shaped configuration))) and (grid near array)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/11 08:10
23	13	("5477082" "5491303" "5517041" "5535101" "5585675" "5640048" "5666024" "5764485" "5875102" "6107109" "6310398" "6380060" "6403460" "2002/0149102").PN.	USPAT	2004/03/11 08:13
24	13	("5477082" "5491303" "5517041" "5535101" "5585675" "5640048" "5666024" "5764485" "5875102" "6107109" "6310398" "6380060" "6403460" "2002/0149102").PN.	USPAT	2004/03/11 08:15
20	20	((bond bonding conductive) adj (land pad)) near3 (shape shaped configuration) with stress	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/11 08:25
25	1279	(bond bonding conductive) adj land	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/11 08:28
26	115	((bond bonding conductive) adj land) with (shape shaped configuration)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/11 08:30
27	67	((substrate carrier ((circuit wiring) near board)) with (trace pattern wiring)) and (((bond bonding conductive) adj land) with (shape shaped configuration))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/11 08:30
28	25	(((substrate carrier ((circuit wiring) near board)) with (trace pattern wiring)) and (((bond bonding conductive) adj land) with (shape shaped configuration))) and stress	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/11 08:30
29	9	("3871015" "4801998" "5186383" "5269453" "5326794" "5346118" "5381307" "5400950" "5576362").PN.	USPAT	2004/03/11 08:32
30	8	6091155.URPN.	USPAT	2004/03/11 08:37